

## **100V P-Channel Trench MOSFET**

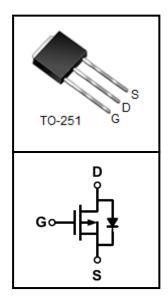
### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information				
Device	Package	Marking		
CTU10P060	TO-251	CTU10P060		

Absolute Maximum Ratings at T <sub>j</sub> = 25°C unless otherwise noted					
Parameter		Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)		$V_{DSS}$	-100	V	
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)		-40	Α	
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)	I <sub>D</sub>	-28	Α	
Pulsed Drain Current	(note2)	I <sub>DM</sub>	-72	А	
Gate Source Voltage		$V_{GSS}$	±20	V	
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	240	mJ	
Power Dissipation T <sub>C</sub> = 25°C	(note4)	$P_{D}$	74.9	W	
Operating Junction and Storage Temperature Range		$T_J,T_stg$	-55~+175	°C	

Thermal Characteristics				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-Case	(note1)	$R_{ heta JC}$	1.2	°C/W
Thermal Resistance, Junction-to-Ambient	(note1)	$R_{\theta JA}$	62	°C/W



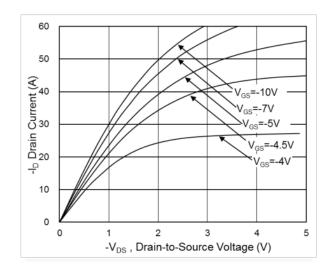
Electrical Characteristics T <sub>j</sub> = 25°C unless otherwise specified								
Parameter	Symbol	Took Conditions	Value					
		Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	-100			V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -100V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			-50	uA		
Zero Gate Voltage Brain Garrent		$V_{DS} = -100V, V_{GS} = 0V, T_{J} = 55^{\circ}C$			-60	uA		
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$			±100	nA		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1.2		-2.5	V		
Drain-Source On-Resistance (note2)	R <sub>DS(on)</sub>	$V_{GS} = -10V, I_D = -12A$	-	46	60	mΩ		
		$V_{GS} = -4.5V, I_{D} = -9A$		48	68	mΩ		
Dynamic								
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ , $V_{DS} = -25V$ ,		6516		pF		
Output Capacitance	$C_{oss}$			223				
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0MHz	1	125				
Total Gate Charge (4.5V)	$Q_g$		-	92		пС		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = -80V, I_{D} = -15A,$ $V_{GS} = -10V$		17.5				
Gate-Drain Charge	$Q_gd$		-	14				
Turn-on Delay Time	t <sub>d(on)</sub>			20.5				
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = -50V, I_{D} = -15A$	1	32.2		ns		
Turn-off Delay Time	$t_{d(off)}$	$V_{GS} = -10V, R_{G} = 3.3\Omega$	1	123				
Turn-off Fall Time	t <sub>f</sub>		1	63.7				
<b>Body Diode Characteristics</b>								
Continuous Body Diode Current	Is	T <sub>C</sub> = 25 °C			-40	А		
Pulsed Diode Forward Current	I <sub>SM</sub>	1 <sub>C</sub> = 20 · O			-72	Α.		
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C$ , $I_{SD} = -1A$ , $V_{GS} = 0V$			1.2	V		
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -14A		31.2		ns		
Reverse Recovery Charge	$Q_{rr}$	$di_F/dt = 100A/\mu s$		31.97		nC		

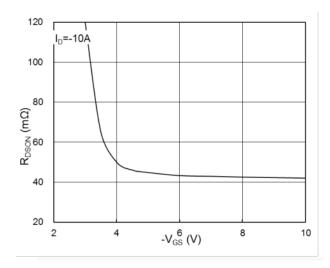
#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\leq\!300\text{us}$  , duty cycle  $\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V, VGS =10V, L=0.85mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- $5. \ The \ data \ is \ theoretically \ the \ same \ as \ ID \ and \ IDM \ , \ in \ real \ applications \ , \ should \ be \ limited \ by \ total \ power \ dissipation.$



## **Typical Characteristics** $T_J = 25$ °C, unless otherwise noted





**Fig.1 Typical Output Characteristics** 

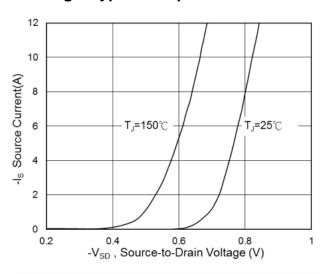


Fig.2 On-Resistance vs. G-S Voltage

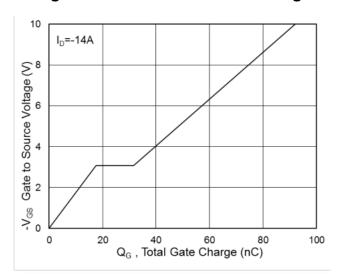


Fig.3 Forward Characteristics of Reverse Diode

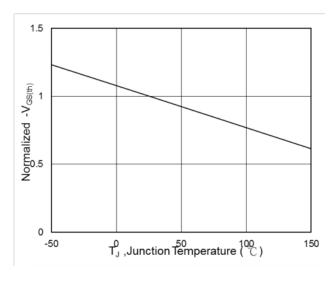


Fig.4 Gate-Charge Characteristics

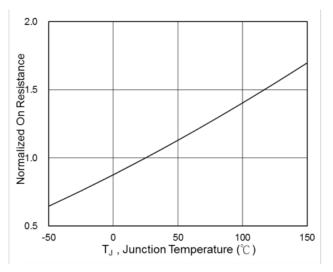


Fig.5 Normalized VGS(th) vs. TJ

Fig.6 Normalized RDSON vs. TJ



## **Typical Characteristics** $T_J = 25$ °C, unless otherwise noted

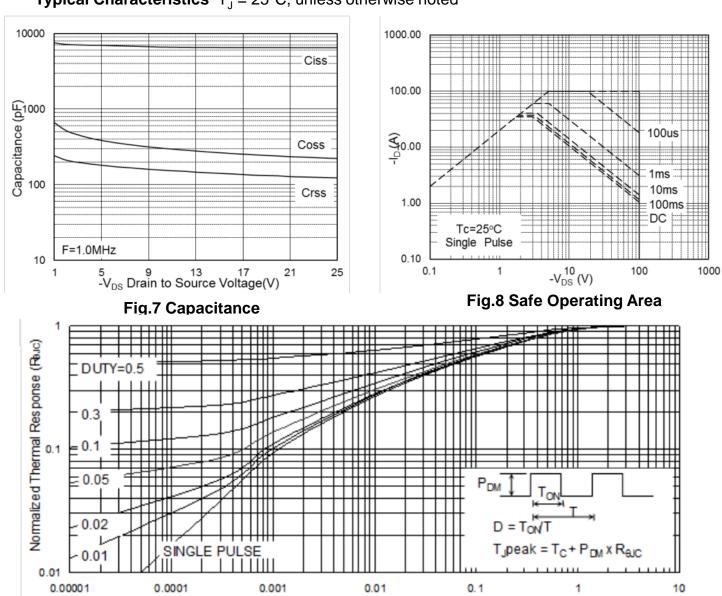


Fig.9 Normalized Maximum Transient Thermal Impedance

t, Pulse Width (s)



Figure A: Gate Charge Test Circuit and Waveform

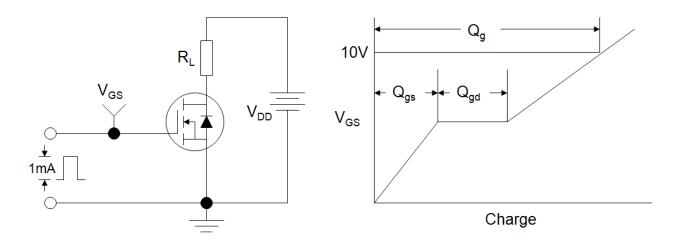


Figure B: Resistive Switching Test Circuit and Waveform

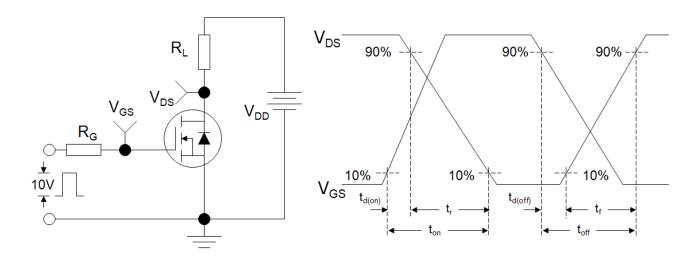
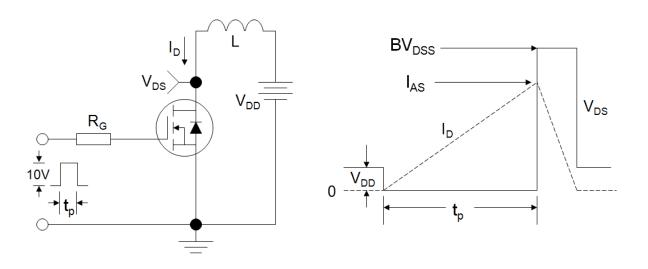
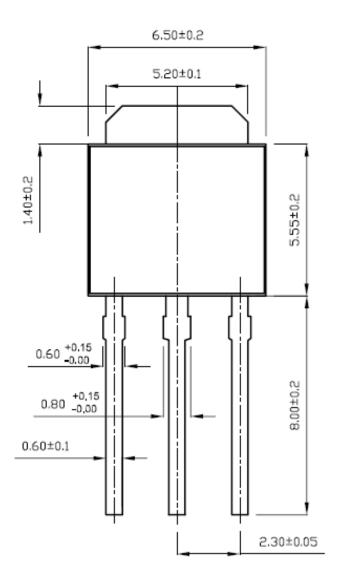


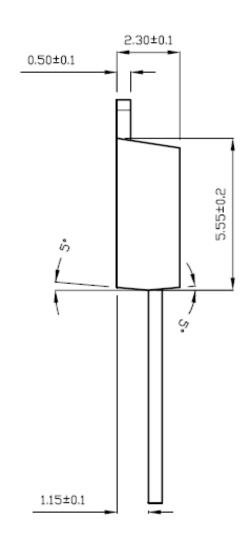
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# TO-251







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